

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	242694	257/\$.ccls. 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	881	1 and airtight	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	76	2 and ((ceramic or (transparent adj glass)) adj (substrate or insulat\$3 or body))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L4	55	3 and (IC or chip or circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	31	4 and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	2	5 and fus\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L8	542	(Hyodo-Haruo or Kimura-Shigeo or Takano-Yasuhiro).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L9	14	8 and airtight	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L10	304	2 and (cap or lid or (glass adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L11	4	9 and (cap or lid or (glass adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	L12	46716	((ceramic or (transparent adj glass)) adj (substrate or insulat\$3 or body))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	L13	4688	12 and (cap or lid or (glass adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	L14	147	13 and airtight	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	L15	103	14 and (IC or chip or circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	L16	46	15 and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16	BRS	L17	5	16 and fus\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB